

- ★ 100% EAS Guaranteed
- ★ Green Device Available
- ★ Super Low Gate Charge
- ★ Excellent CdV/dt effect decline
- ★ Advanced high cell density Trench technology

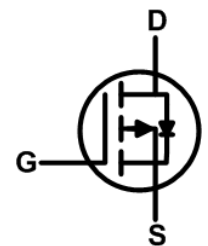
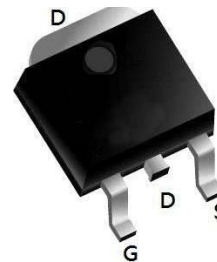

Product Summary

BVDSS	RDSON	ID
-30V	6.0mΩ	-80A

Description

The XXW80P03 is the highest performance trench P-ch MOSFETs with extreme high cell density, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications .

The XXW80P03 meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

TO252 Pin Configuration

Absolute Maximum Ratings

Parameter		Symbol	Value	Unit
Drain-Source Voltage		V_{DS}	-30	V
Gate-Source Voltage		V_{GS}	±20	V
Continuous Drain Current@-10V ¹	$T_C=25^{\circ}C$	I_D	-80	A
	$T_C=75^{\circ}C$		-42	
Pulsed Drain Current ²		I_{DM}	-175	A
Single Pulse Avalanche Energy ³		EAS	31	mJ
Avalanche Current		I_{AS}	-25	A
Total Power Dissipation ⁴	$T_C=25^{\circ}C$	P_D	31.2	W
Operating Junction and Storage Temperature Range		T_J, T_{STG}	-55 to+150	°C

Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal Resistance from Junction-to-Ambient ¹	$R_{\theta JA}$	43	°C/W
Thermal Resistance from Junction-to-Case ¹	$R_{\theta JC}$	4	°C/W

Electrical Characteristics $T_c = 25^\circ\text{C}$, unless otherwise noted

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = -250\mu A$	-30	-	-	V
Gate-body Leakage current	I_{GSS}	$V_{DS} = 0V, V_{GS} = \pm 20V$	-	-	± 100	nA
Zero Gate Voltage Drain Current	$T_J = 25^\circ\text{C}$	$V_{DS} = -24V, V_{GS} = 0V$	-	-	-1	μA
	$T_J = 55^\circ\text{C}$		-	-	-5	
Gate-Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = -250\mu A$	-1.0	-1.6	-2.5	V
Drain-Source On-Resistance ²	$R_{DS(on)}$	$V_{GS} = -10V, I_D = -12A$	-	6	8.8	m Ω
		$V_{GS} = -4.5V, I_D = -8A$	-	9	14	
Forward Transconductance	g_{fs}	$V_{DS} = -5V, I_D = -20A$	-	28	-	S
Dynamic Characteristics						
Input Capacitance	C_{iss}	$V_{DS} = -15V, V_{GS} = 0V, f = 1\text{MHz}$	-	4320	-	pF
Output Capacitance	C_{oss}		-	529	-	
Reverse Transfer Capacitance	C_{rss}		-	487	-	
Switching Characteristics						
Gate Resistance	R_g	$V_{DS} = 0V, V_{GS} = 0V, f = 1.0\text{MHz}$	-	4.0	-	Ω
Total Gate Charge	Q_g	$V_{GS} = -10V, V_{DS} = -15V, I_D = -15A$	-	45	-	nC
Gate-Source Charge	Q_{gs}		-	8.5	-	
Gate-Drain Charge	Q_{gd}		-	12.8	-	
Turn-On Delay Time	$t_{d(on)}$	$V_{GS} = -10V, V_{DD} = -15V, R_G = 2.5\Omega, I_D = -15A$	-	18.9	-	nS
Rise Time	t_r		-	15.7	-	
Turn-Off Delay Time	$t_{d(off)}$		-	64.8	-	
Fall Time	t_f		-	36.5	-	
Drain-Source Body Diode Characteristics						
Diode Forward Voltage ²	V_{SD}	$I_S = -1A, V_{GS} = 0V$	-	-	-1	V
Continuous Source Current ^{1,5}	I_S	$V_G = V_D = 0V$, Force Current	-	-	-80	A

Note :

- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$
- 3.The EAS data shows Max. rating . The test condition is $V_{DD} = -25V, V_{GS} = -10V, L = 0.1\text{mH}, I_{AS} = -25A$
- 4.The power dissipation is limited by 150°C junction temperature
- 5.The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.

P-Ch 30V Fast Switching MOSFETs

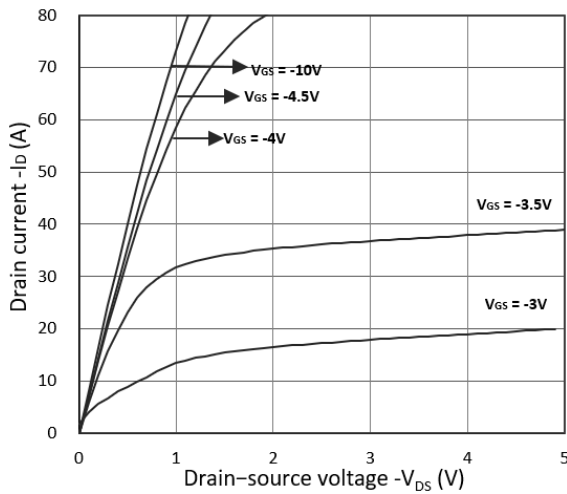


Figure 1. Output Characteristics

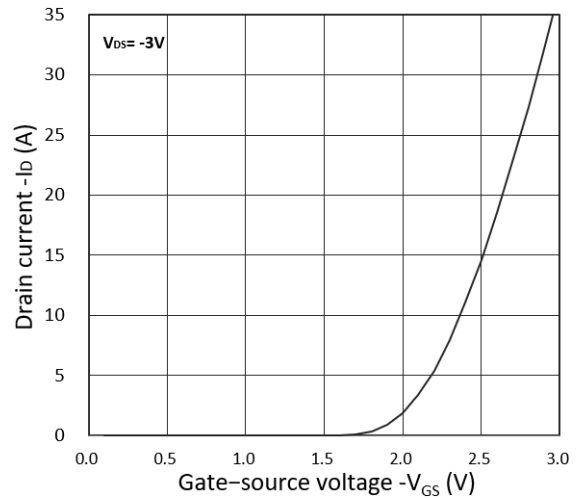


Figure 2. Transfer Characteristics

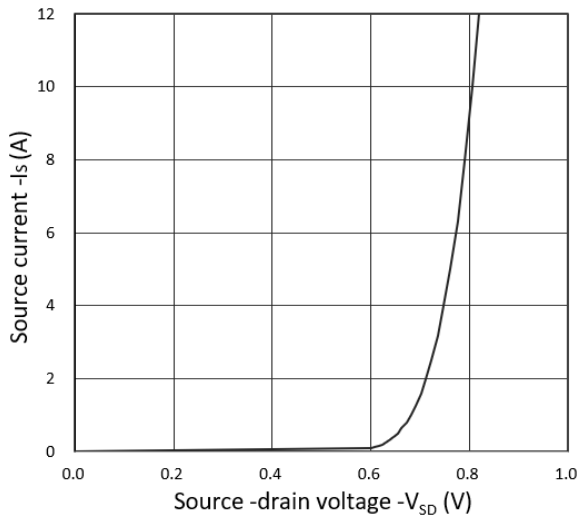


Figure 3. Forward Characteristics of Reverse

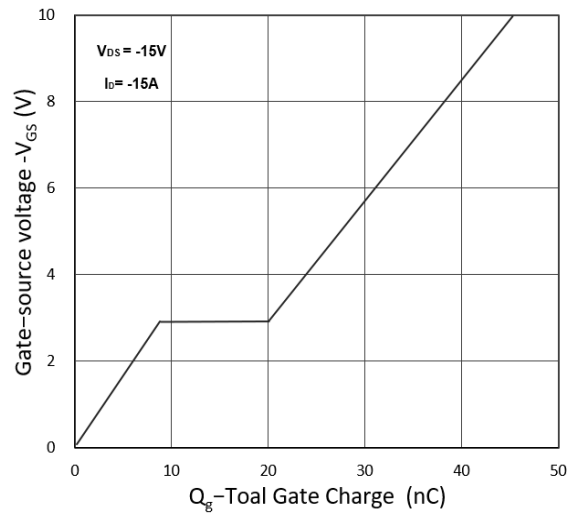


Figure 4. Gate Charge Characteristics

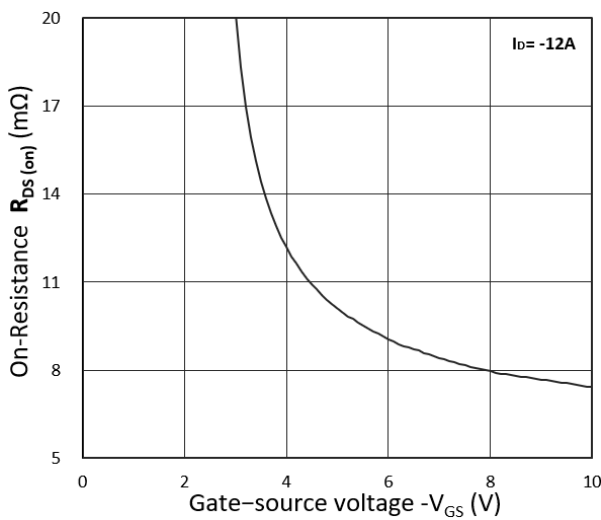


Figure 5. $R_{DS(on)}$ vs. V_{GS}

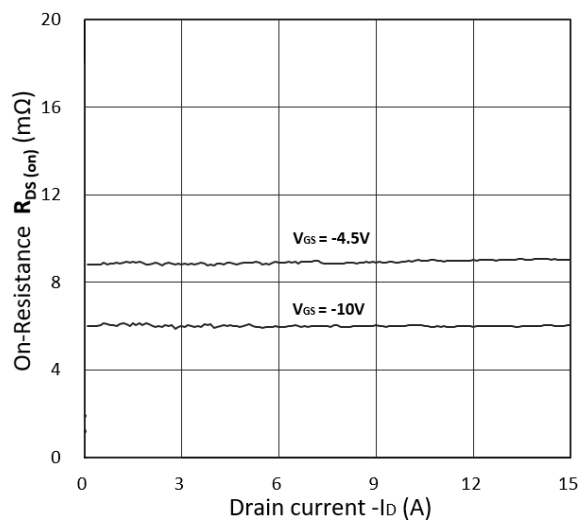


Figure 6. $R_{DS(on)}$ vs. I_D

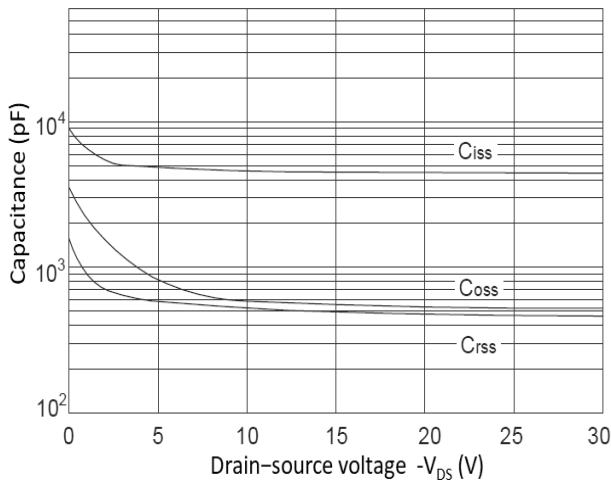
P-Ch 30V Fast Switching MOSFETs


Figure 7. Capacitance Characteristics

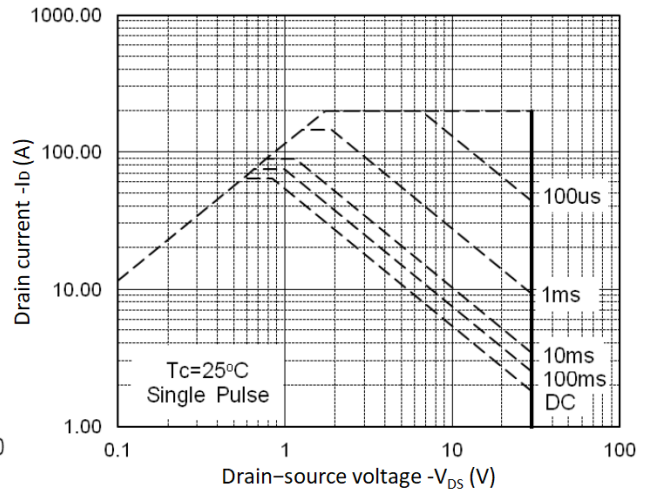


Figure 8. Safe Operating Area

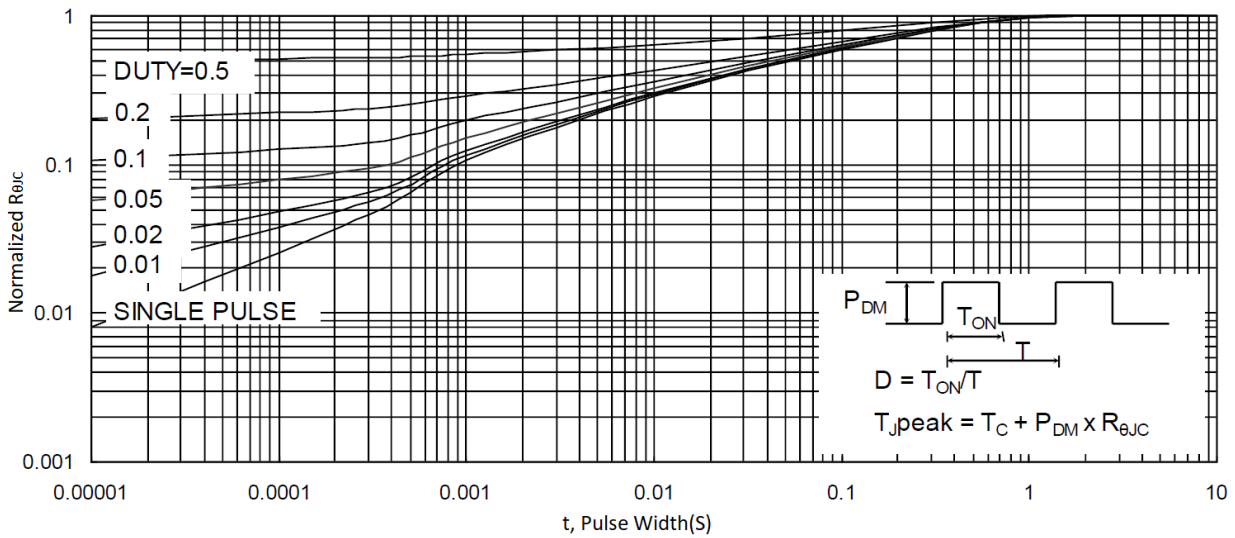


Figure 9. Normalized Maximum Transient Thermal Impedance

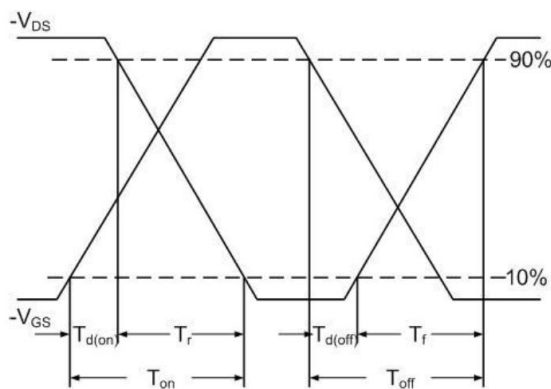


Figure 10. Switching Time Waveform

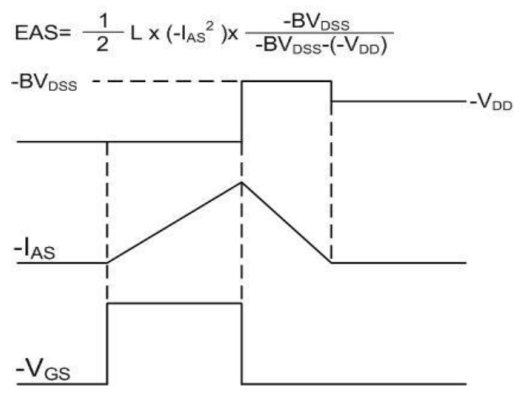
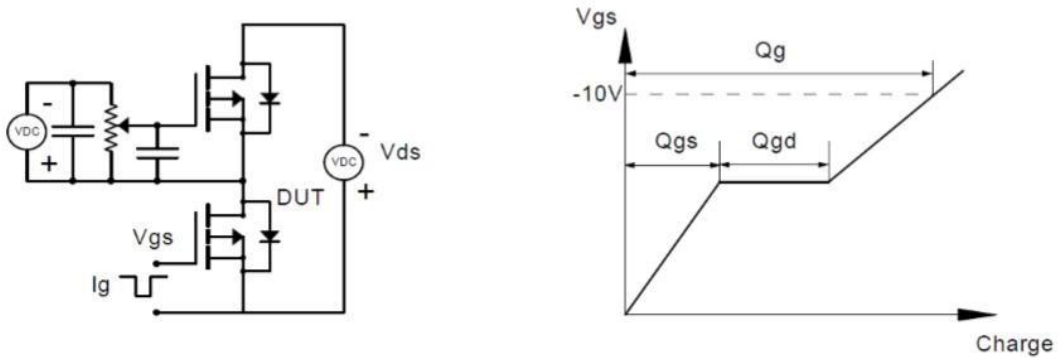
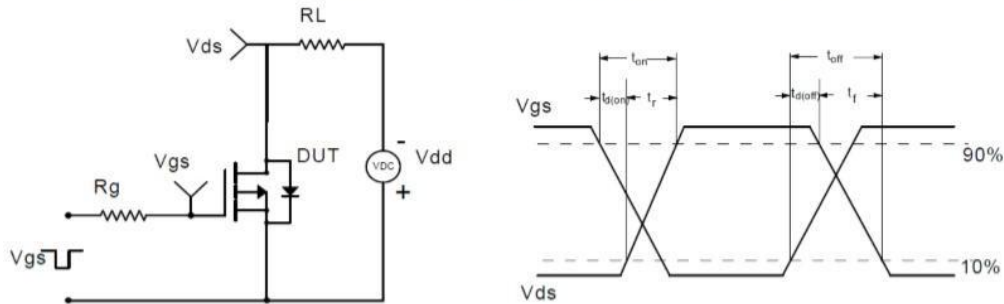
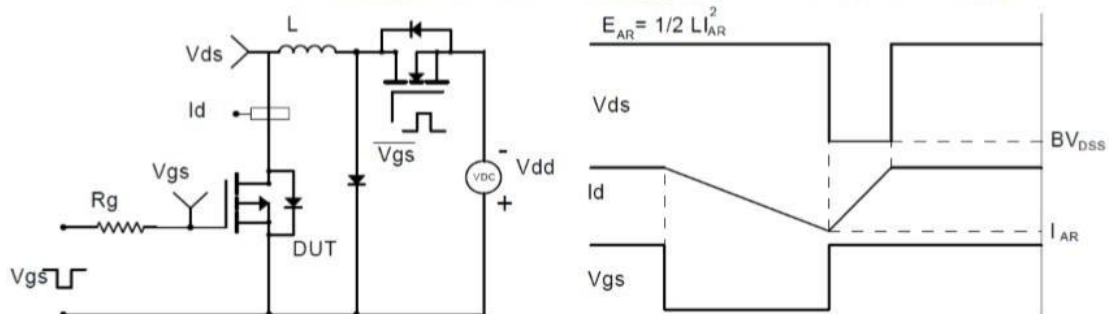
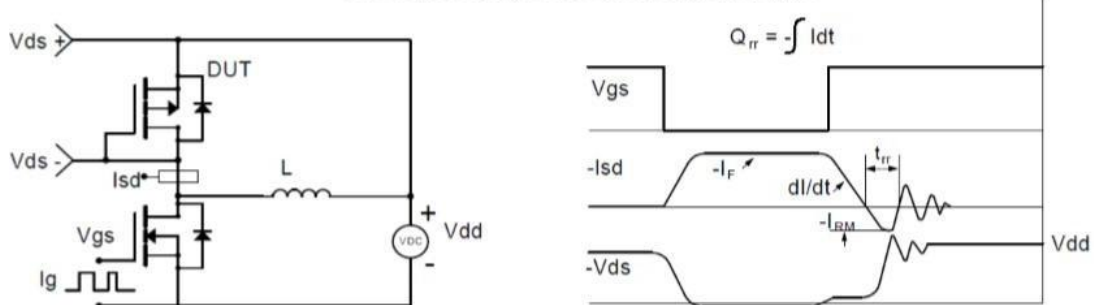
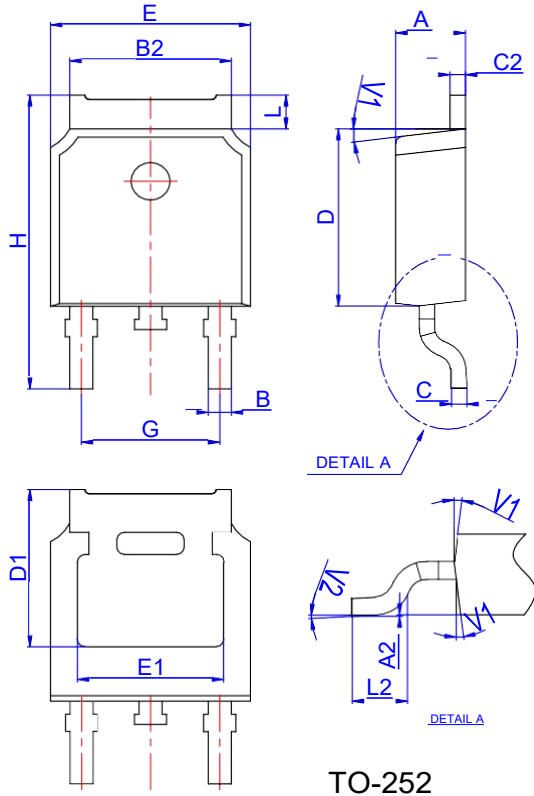
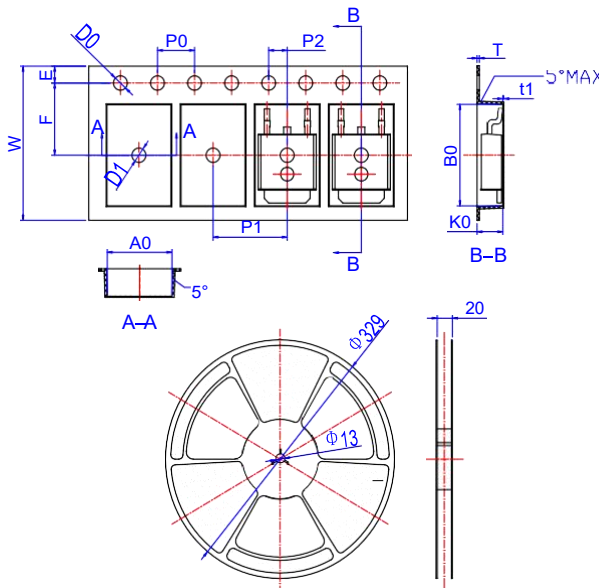


Figure 11. Unclamped Inductive Switching Waveform

Test Circuit
Gate Charge Test Circuit & Waveform

Resistive Switching Test Circuit & Waveforms

Unclamped Inductive Switching (UIS) Test Circuit & Waveforms

Diode Recovery Test Circuit & Waveforms


Package Mechanical Data TO 252


Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	2.10		2.50	0.083		0.098
A2	0		0.10	0		0.004
B	0.66		0.86	0.026		0.034
B2	5.18		5.48	0.202		0.216
C	0.40		0.60	0.016		0.024
C2	0.44		0.58	0.017		0.023
D	5.90		6.30	0.232		0.248
D1	5.30REF			0.209REF		
E	6.40		6.80	0.252		0.268
E1	4.63			0.182		
G	4.47		4.67	0.176		0.184
H	9.50		10.70	0.374		0.421
L	1.09		1.21	0.043		0.048
L2	1.35		1.65	0.053		0.065
V1		7°			7°	
V2	0°		6°	0°		6°

Reel Specification-TO-252-4R


Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
W	15.90	16.00	16.10	0.626	0.630	0.634
E	1.65	1.75	1.85	0.065	0.069	0.073
F	7.40	7.50	7.60	0.291	0.295	0.299
D0	1.40	1.50	1.60	0.055	0.059	0.063
D1	1.40	1.50	1.60	0.055	0.059	0.063
P0	3.90	4.00	4.10	0.154	0.157	0.161
P1	7.90	8.00	8.10	0.311	0.315	0.319
P2	1.90	2.00	2.10	0.075	0.079	0.083
A0	6.85	6.90	7.00	0.270	0.271	0.276
B0	10.45	10.50	10.60	0.411	0.413	0.417
K0	2.68	2.78	2.88	0.105	0.109	0.113
T	0.24		0.27	0.009		0.011
t1	0.10			0.004		
10P0	39.80	40.00	40.20	1.567	1.575	1.583